CLAIMS

1. An apparatus comprising:

a measurement chamber, wherein the measurement chamber has a removable lid; and

a plurality of wafer support elements for supporting a wafer from beneath, wherein the plurality of wafer support elements are provided on the lid.

2. The apparatus according to claim 1, wherein:

the wafer support elements are provided on an underside of the lid; and/or

the wafer support elements are wafer hangers; and/or

the wafer support elements are configured to suspend the wafer beneath the underside of the lid; and/or

there are exactly three of the wafer support elements, optionally wherein contact points of the three wafer support elements are configured to be evenly spaced around a circumference of the wafer when the wafer is supported by the three wafer support elements; and/or

each of the plurality of wafer support elements is substantially L-shaped; and/or

each of the plurality of wafer support elements is configured to extend inwards relative to a wafer supported by the plurality of wafer support elements.

3. The apparatus according to claim 1 or 2, wherein the lid is a top surface of the measurement chamber.

4. The apparatus according to any one of the preceding claims, wherein the lid is movable vertically upwards relative to a main body of the measurement chamber to remove the lid from the main body of the measurement chamber, and movable vertically downwards relative to the main body of the measurement chamber to position the lid on the main body of

the measurement chamber, optionally wherein the apparatus comprises one or more actuators connected or coupled to the lid and operable to move the lid relative to the main body of the measurement chamber.

5. The apparatus according to any one of the preceding claims, wherein:

the apparatus comprises a weighing device for performing a weight measurement on a wafer; and

the weighing device is inside the measurement chamber,

optionally wherein the apparatus is configured so that the wafer is loaded onto the weighing device from the wafer support elements when the lid is positioned on the measurement chamber.

6. The apparatus according to claim 5, wherein:

the weighing device comprises a support for supporting the wafer during the weight measurement; and

the apparatus is configured so that the wafer is loaded onto the support from the wafer support elements when the lid is positioned on the measurement chamber,

optionally wherein the support comprises a plurality of contact elements configured to contact an underside of the wafer to support the wafer during the weight measurement, and further optionally wherein when the lid is positioned on the measurement chamber, contact points of the contact elements are vertically higher than contact points of the wafer support elements.

7. The apparatus according to any one of the preceding claims, wherein the apparatus comprises a seal that is located between the lid and the measurement chamber when the lid is positioned on the measurement chamber.

8. The apparatus according to claim 5 or 6, wherein the weighing device is for performing a weight measurement on a wafer having a specific diameter D, the weighing device comprising a support for supporting the wafer during the weight measurement, wherein:

the support comprises a plurality of contact elements configured to contact an underside of the wafer less than or equal to a distance of D/3, or D/4, or D/5, or D/6, or D/7, or D/8, or D/9, or D/10, or D/11, or D/12, or D/13, or D/14, or D/15, or D/16, or D/17, or D/18, or D/19, or D/20 from an edge of the wafer, to support the wafer during the weight measurement.

9. The apparatus according to claim 8, wherein

the plurality of contact elements comprise pins; and/or

the weighing device is for performing a weight measurement on a wafer having a diameter of 200 mm, or 300 mm, or 450 mm; and/or

the plurality of contact elements comprise two or more different lengths of contact element, optionally wherein the plurality of contact elements comprise two or more different lengths of contact element so as to support the wafer in a more level orientation; and/or

one or more of the plurality of contact elements has an adjustable length.

10. The apparatus according to claim 8 or 9, wherein:

the plurality of wafer support elements are for supporting the wafer from beneath while the wafer is being loaded onto the support; and

a contact element of the plurality of contact elements is configured to contact the underside of the wafer less than or equal to 50 mm from a position where a wafer support element of the plurality of wafer support elements is configured to contact the underside of the wafer,

optionally wherein:

the contact element is configured to contact the underside of the wafer less than or equal to 40 mm, or 30 mm, or 20 mm, or 10 mm, from the position where the wafer support element is configured to contact the underside of the wafer; and/or

each of the plurality of contact elements is configured to contact the underside of the wafer less than or equal to 50 mm, or 40 mm, or 30 mm, or 20 mm, or 10 mm from a position where a wafer support element of the plurality of wafer support elements is configured to contact the underside of the wafer.

11. The apparatus according to claim 5 or 6, wherein the weighing device comprises a support for supporting the wafer during the weight measurement, wherein:

the support comprises a plurality of contact elements located at least 50 mm from a centre of the support and configured to contact an underside of the wafer to support the wafer during the weight measurement,

optionally wherein the plurality of contact elements are located at least 60 mm, or at least 70 mm, or at least 75 mm, or at least 80 mm, or at least 90 mm, or at least 100 mm, or at least 110 mm, or at least 120 mm, or at least 130 mm, or at least 140 mm, from the centre of the support.

12. The apparatus according to claim 5 or 6, wherein:

the weighing device comprises a support for supporting the wafer during the weight measurement, wherein the support comprises a plurality of contact elements configured to contact an underside of the wafer to support the wafer during the weight measurement;

the plurality of wafer support elements are for supporting the wafer from beneath while the wafer is being loaded onto the support; and

a contact element of the plurality of contact elements is configured to contact the underside of the wafer less than or equal to 50 mm from a position where a wafer support element of the plurality of wafer support elements is configured to contact the underside of the wafer,

optionally wherein:

the contact element is configured to contact the underside of the wafer less than or equal to 40 mm, or 30 mm, or 20 mm, or 10 mm, from the position where the wafer support element is configured to contact the underside of the wafer; and/or

each of the plurality of contact elements is configured to contact the underside of the wafer less than or equal to 50 mm, or 40 mm, or 30 mm, or 20 mm, or 10 mm from a position where a wafer support element of the plurality of wafer support elements is configured to contact the underside of the wafer.

13. The apparatus according to claim 12, wherein:

the plurality of contact elements comprise pins; and/or

the plurality of contact elements comprise two or more different lengths of contact element, optionally wherein the plurality of contact elements comprise two or more different lengths of contact element so as to support the wafer in a more level orientation during the weight measurement; and/or

one or more of the plurality of contact elements has an adjustable length.

14. The apparatus according to claim 12 or 13, wherein:

the weighing device is for performing a weight measurement on a wafer having a specific diameter D, and one of more of the plurality of contact elements is configured to contact an underside of the wafer less than or equal to a distance of D/3, or D/4, or D/5, or D/6, or D/7, or D/8, or D/9, or D/10, or D/11, or D/12, or D/13, or D/14, or D/15, or

D/16, or D/17, or D/18, or D/19, or D/20 from an edge of the wafer; and/or

one or more of the plurality of contact elements is located at least 50 mm, or at least 60 mm, or at least 70 mm, or at least 75 mm, or at least 80 mm, or at least 90 mm, or at least 100 mm, or at least 110 mm, or at least 120 mm, or at least 130 mm, or at least 140 mm from a centre of the support.

15. The apparatus according to claim 5 or 6, wherein the weighing device comprises a support for supporting the wafer during the weight measurement, wherein:

the support comprises a plurality of contact elements configured to contact an underside of the wafer to support the wafer during the weight measurement; and

the plurality of contact elements include two or more different lengths of contact element,

optionally wherein:

the plurality of contact elements comprise two or more different lengths of contact element so as to support the wafer in a more level orientation during the weight measurement; and/or

at least one of the plurality of contact elements has an adjustable length.